INTEGRATED CIRCUITS

DATA SHEET

74F456

Octal buffer/driver with parity, non-inverting (3-State)

Product specification
Supersedes data of 1999 Jan 08
IC15 Data Handbook





Octal buffer/driver with parity, non-inverting (3-State)

74F456

FEATURES

- High impedance NPN base inputs for reduced loading (40μA in High and Low states)
- 74F456 combines 74F244 and 74F280A functions in one package
- 74F456 is a center pin version of the 74F656A
- Non-Inverting
- 3-State outputs sink 64mA and source 15mA
- 24-pin plastic Slim DIP (300 mil) package
- Broadside pinout simplifies PC board layout

DESCRIPTION

The 74F456 is an octal buffer and line driver with parity generation/checking designed to be employed as memory address drivers, clock drivers and bus-oriented transmitters/receivers. These parts include parity generator/checker to improve PC board density.

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F456	7.5ns	64mA

ORDERING INFORMATION

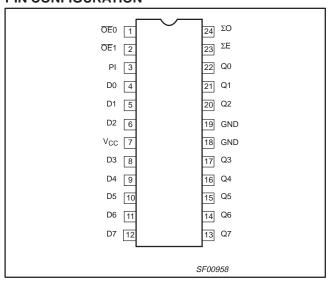
DESCRIPTION		PKG DWG #
24-pin plastic Slim DIP (300mil)	N74F456N	SOT222-1
24-pin plastic SOL	N74F456D	SOT137-1

INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

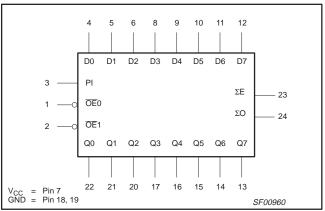
PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
D0-D7	Data inputs	2.0/0.066	40μΑ/40μΑ
PI	Parity input	1.0/0.033	20μΑ/20μΑ
OE0, OE1	Output Enable inputs (active Low)	1.0/0.033	20μΑ/20μΑ
ΣΕ, ΣΟ	Parity outputs	750/106.7	15mA/64mA
Q0-Q7	Data outputs	750/106.7	15mA/64mA

NOTE: One (1.0) FAST Unit Load (U.L.) is defined as 20μA in the High state and 0.6mA in the Low state.

PIN CONFIGURATION



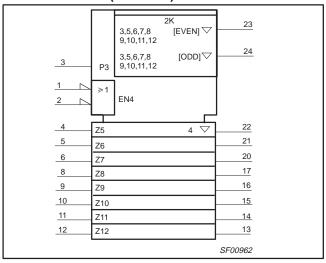
LOGIC SYMBOL



Octal buffer/driver with parity, non-inverting (3-State)

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LOGIC SYMBOL (IEEE/IEC)



FUNCTION TABLE

	OUTPUTS		
OE0	OE1	Dn	Qn
L	L	L	L
L	L	Н	Н
Н	Х	Х	Z
Х	Н	Х	Z

H = High voltage level
L = Low voltage level
Z = High impedance "off" state
X = Don't care

FUNCTION TABLE for PARITY OUTPUTS

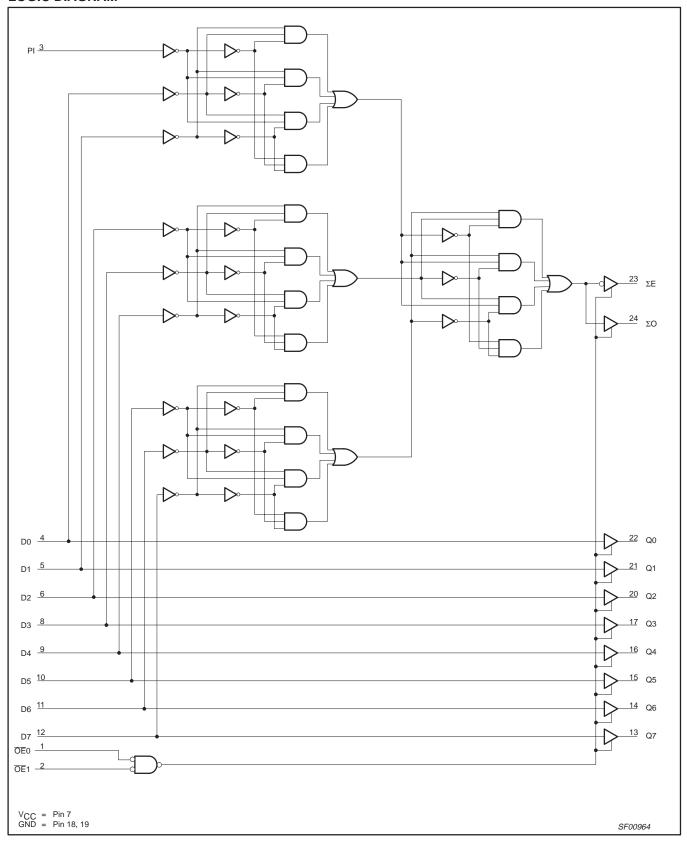
INPUTS	OUTF	PUTS
Number of inputs, High (PI, D0 - D7)	ΣΕ	ΣΟ
Even - 0, 2, 4, 6, 8	Н	L
Odd - 1, 3, 5, 7, 9	L	Н
Any OEn = High	Z	Z

H = High voltage level

L = Low voltage level
Z = High impedance "off" state
X = Don't care

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LOGIC DIAGRAM



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ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V _{CC}	Supply voltage	-0.5 to +7.0	V
V _{IN}	Input voltage	-0.5 to +7.0	V
I _{IN}	Input current	−30 to +5	mA
V _{OUT}	Voltage applied to output in High output state	–0.5 to +V _{CC}	V
I _{OUT}	Current applied to output in Low output state	128	mA
T _{amb}	Operating free-air temperature range	0 to +70	°C
T _{stg}	Storage temperature range	-65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

CVMDOL	DADAMETED		UNIT			
SYMBOL	PARAMETER	MIN	NOM	MAX	UNIT	
V _{CC}	Supply voltage	4.5	5.0	5.5	V	
V _{IH}	High-level input voltage	2.0			V	
V _{IL}	Low-level input voltage			0.8	V	
I _{IK}	Input clamp current			-18	mA	
I _{OH}	High-level output current			-15	mA	
I _{OL}	Low-level output current			64	mA	
T _{amb}	Operating free-air temperature range	0		70	°C	

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DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

OVMDOL	DL PARAMETER TEST CONDITIONS ¹						LIMITS		
SYMBOL	PARAMETER		l ies	MIN	TYP ²	MAX	UNIT		
			V _{CC} = MIN,		±10%V _{CC}	2.4			V
V _{OH}	High-level output voltage		$V_{IL} = MAX$,	I _{OH} =–3mA	±5%V _{CC}	2.7	3.3		V
		$V_{IH} = MIN$	I _{OH} =–15mA	±10%V _{CC}	2.0			V	
	l and land antenderal		$V_{CC} = MIN,$ $V_{II} = MAX,$	I MAN	±10%V _{CC}			0.55	V
V _{OL}	Low-level output voltage		$V_{IH} = IVIAX,$ $V_{IH} = MIN$	I _{OL} = MAX	±5%V _{CC}		0.42	0.55	V
V _{IK}	Input clamp voltage	V _{CC} = MIN, I _I	$V_{CC} = MIN, I_I = I_{IK}$				-1.2	V	
I _I	Input current at maximum input voltage		$V_{CC} = 0.0V, V$	V _{CC} = 0.0V, V _I = 7.0V				100	μΑ
L	High-level input current	Dn	\/ - N AAY \	$V_{CC} = MAX, V_1 = 2.7V$				40	μΑ
IH	High-lever input current	PI, OE n	V _{CC} = IVIAX, V	/ = 2.7 V				20	μΑ
L.	Low-level input current	Dn	V _{CC} = MAX, V	/. = 0.5\/				-40	μΑ
IIL	Low-level input current	PI, OE n	VCC = IVIAX, V	/ = 0.5 v				-20	μΑ
I _{OZH}	Off-state output current High-level voltage applied		V _{CC} = MAX, V	/ _O = 2.7V				50	μΑ
I _{OZL}	Off-state output current Low-level voltage applied		V _{CC} = MAX, V	$V_{CC} = MAX, V_O = 0.5V$				-50	μΑ
I _{OS}	Short-circuit output current ³		$V_{CC} = MAX$	V _{CC} = MAX		-100		-225	mA
		I _{CCH}					50	80	mA
I _{CC}	Supply current (total)	I _{CCL}	$V_{CC} = MAX$	$V_{CC} = MAX$			78	110	mA
						63	90	mA	

For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
 All typical values are at V_{CC} = 5V, T_{amb} = 25°C.

AC ELECTRICAL CHARACTERISTICS

					LIM	ITS		
SYMBOL	PARAMETER	TEST CONDITION	V_{CC} = +5V T_{amb} = +25°C C_L = 50pF, R_L = 500 Ω			V _{CC} = +5 T _{amb} = 0°C C _L = 50pF,	UNIT	
			MIN	TYP	MAX	MIN	MAX	
t _{PLH} t _{PHL}	Propagation delay Dn to Qn	Waveform 1	2.0 2.5	4.5 5.0	6.5 7.0	2.0 2.5	7.0 7.5	ns
t _{PLH} t _{PHL}	Propagation delay Dn to $\Sigma E, \Sigma O$	Waveform 1, 2	5.5 5.5	10.0 11.0	13.0 14.5	5.5 5.5	14.0 16.5	ns
t _{PZH} t _{PZL}	Output Enable time to High or Low level	Waveform 3 Waveform 4	2.5 4.0	4.0 8.0	8.0 10.5	2.5 4.0	9.0 11.5	ns
t _{PHZ} t _{PLZ}	Output Disable time from High or Low level	Waveform 3 Waveform 4	1.5 2.0	4.0 5.0	6.5 7.5	1.5 2.0	7.5 8.0	ns

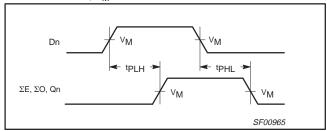
Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

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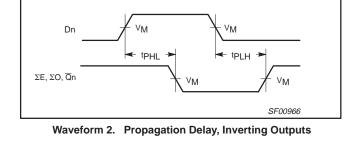
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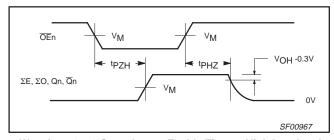
AC WAVEFORMS

For all waveforms, $V_M = 1.5V$.

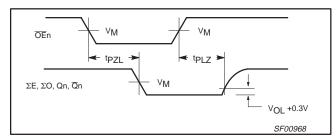


Waveform 1. Propagation Delay, Non-Inverting Outputs



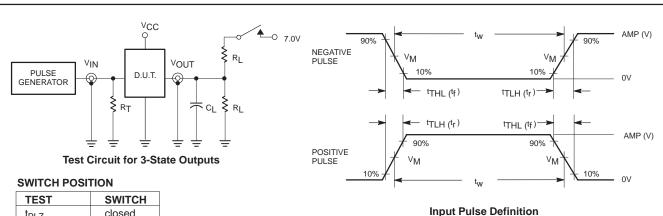


Waveform 3. 3-State Output Enable Time to High Level and Output Disable Time from High Level



Waveform 4. 3-State Output Enable Time to Low Level and Output Disable Time from Low Level

TEST CIRCUIT AND WAVEFORMS



TEST	SWITCH
t _{PLZ}	closed
t _{PZL}	closed
All other	open

DEFINITIONS:

R_L = Load resistor;

see AC electrical characteristics for value.

C_L = Load capacitance includes jig and probe capacitance; see AC electrical characteristics for value.

 $R_T = Termination resistance should be equal to <math display="inline">Z_{OUT}$ of pulse generators.

family	INP	UT PU	LSE REQU	IREMEN	TS	
laililly	amplitude	V_{M}	rep. rate	t _w	t _{TLH}	t _{THL}
74F	74F 3.0V 1.5V		1MHz	500ns	2.5ns	2.5ns

SF00777

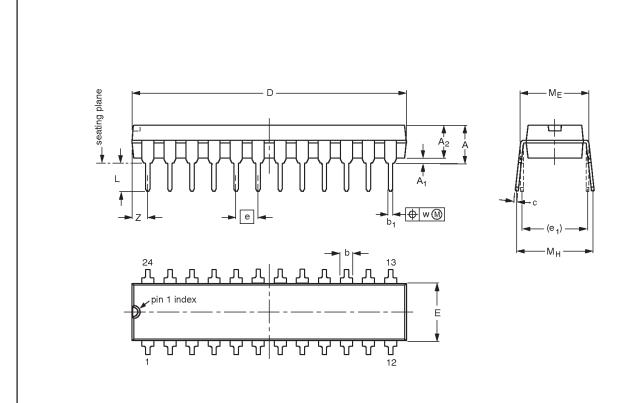
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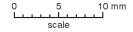
Octal buffer/driver with parity, non-inverting (3-State)

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DIP24: plastic dual in-line package; 24 leads (300 mil)

SOT222-1





DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	С	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	ME	Мн	w	Z ⁽¹⁾ max.
mm	4.70	0.38	3.94	1.63 1.14	0.56 0.43	0.36 0.25	31.9 31.5	6.73 6.48	2.54	7.62	3.51 3.05	8.13 7.62	10.03 7.62	0.25	2.05
inches	0.185	0.015	0.155	0.064 0.045	0.022 0.017	0.014 0.010	1.256 1.240	0.265 0.255	0.100	0.300	0.138 0.120	0.32 0.30	0.395 0.300	0.01	0.081

Note

1. Plastic or metal protrusions of 0.01 inches maximum per side are not included.

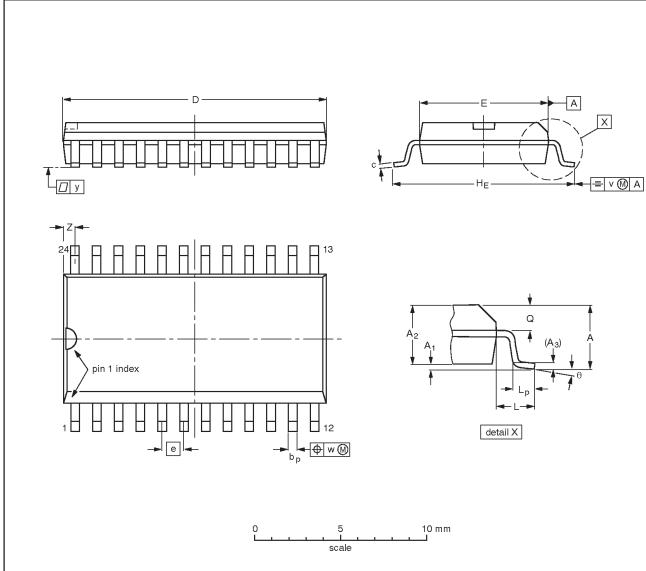
OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT222-1		MS-001AF				95-03-11

Octal buffer/driver with parity, non-inverting (3-State)

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SO24: plastic small outline package; 24 leads; body width 7.5 mm

SOT137-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	А3	bр	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	15.6 15.2	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.61 0.60	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE		
SOT137-1	075E05	MS-013AD			-95-01-24 97-05-22		

Octal buffer/driver with parity, non-inverting (3-State)

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Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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^[1] Please consult the most recently issued datasheet before initiating or completing a design.

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Date of release: 08-00

Document order number: 9397-750 -07378

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